

Application No.: 09/817,843

Docket No.: 20135-00310-US

**In the Claims:****Please cancel claims 4-16 and 22-34.****Please amend claim 17 as follows:**

B 17. (Amended) A springboard contact pad - laminate surface contact structure comprising:

a semiconductor substrate having a major surface;

a first mechanically compliant dielectric layer formed over said major surface of said substrate and having at least one first opening formed therethrough;

a first electrical contact pad formed in said first opening and in electrical contact with said substrate;

a second mechanically compliant dielectric layer formed over said first compliant layer and having at least one second opening formed therethrough wherein said second opening is substantially offset from said first opening;

a second electrical contact pad formed in said second opening and extending over a portion of said first electrical contact pad and contacting said first electrical contact pad;

a mask layer formed over said second compliant layer and having a third opening therethrough in communication with said second electrical contact pad; and

a solder ball solderably connected to said second electrical contact pad and extending through said third opening.

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**Please add new claims 35-37:**

B<sup>2</sup>  
35. (New) An electronic package having selectively controlled contact pad - laminate surface adhesion, according to claim 1, wherein the smooth portion of the conductive foil has a surface roughness less than about 2.0 micron.

36. (New) An electronic package having selectively controlled contact pad - laminate surface adhesion, according to claim 35, wherein the smooth portion of the conductive foil has a surface roughness less than about 1.0 micron.

37. (New) An electronic package having selectively controlled contact pad - laminate surface adhesion, according to claim 36, wherein the smooth portion of the conductive foil has a surface roughness less than about 0.01 micron.